TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOSVI)

2 S K 3 1 2 9

CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

Low Drain-Source ON Resistance : $R_{DS(ON)} = 5.5 \text{ m}\Omega$ (Typ.)

High Forward Transfer Admittance: $|Y_{fs}| = 70 \text{ S}$ (Typ.)

Low Leakage Current : $I_{DSS} = 100 \,\mu\text{A}$ (Max.) ($V_{DS} = 30 \,\text{V}$)

: $V_{th} = 0.8 \sim 2.0 \text{ V}$ Enhancement-Mode

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTE	SYMBOL	RATING	UNIT	
Drain-Source Voltage	${ m v_{DSS}}$	50	V	
Drain-Gate Voltage ($v_{ m DGR}$	50	V	
Gate-Source Voltage	v_{GSS}	±20	V	
Drain Current	DC (Note 1)	$I_{\mathbf{D}}$	60	A
	Pulse (Note 1)	I_{DP}	240	A
Drain Power Dissipat	$P_{\mathbf{D}}$	150	W	
Single Pulse Avalance	EAS	721	mJ	
Avalanche Current	I_{AR}	60	Α	
Repetitive Avalanche	EAR	12	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	°C	
Storage Temperature	$\mathrm{T_{stg}}$	-55~150	°C	

Unit in mm 15.9 max ø3.2±0.2 1.0 +0.3 5.45±0.2 5.45±0.2 **GATE** DRAIN (HEAT SINK) 3. SOURCE **JEDEC JEITA** SC-65 **TOSHIBA** 2-16C1B

Weight: 4.6 g (Typ.)

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R _{th (ch-c)}	0.833	°C/W
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	50	°C/W

(Note 1): Please use devices on condition that the channel temperature is below 150°C.

(Note 2): $V_{DD}=25\,V$, $T_{ch}=25^{\circ}C$ (initial), $L=246\,\mu H$, $R_{G}=25\,\Omega$, $I_{AR}=60\,A$ (Note 3): Repetitive rating; Pulse Width Limited by maximum junction temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.

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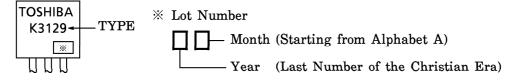
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	e Current	I_{GSS}	$V_{GS} = \pm 16 V, V_{DS} = 0 V$		_	±10	μ A
Drain Cut-off	f Current	$I_{ m DSS}$	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	$\mu \mathbf{A}$
Drain-Source Voltage	Breakdown		$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	50	_	_	V
Gate Thresho	old Voltage	$V_{ m th}$	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	0.8	_	2.0	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$	_	5.5	7	$\mathbf{m}\Omega$
Forward Tran Admittance	nsfer	Y _{fs}	$V_{ m DS} = 10 \ m V, \ I_{ m D} = 30 \ m A$	40	70	_	S
Input Capacitance Reverse Transfer Capacitance		$\mathrm{c}_{\mathrm{iss}}$	$V_{ m DS} = 10 m V, \ V_{ m GS} = 0 m V$ $ m f = 1 MHz$	_	3700	_	pF
		C _{rss}		_	650	_	
Output Capac	Output Capacitance				1800	_	
Switching Time	Rise Time	$egin{array}{c} { m C}_{ m oss} \ { m t}_{ m r} \end{array}$	$V_{GS} \stackrel{10 \text{ V}}{}_{0 \text{ V}} \stackrel{\text{I}_{D} = 30 \text{ A}}{}_{0 \text{ VOUT}}$ $R_{L} = 0.83 \Omega$ $V_{DD} = 25 \text{ V}$ $Duty \leq 1\%, t_{W} = 10 \mu \text{s}$	_	20	_	
	Turn-on Time	ton			35	_	ns
	Fall Time	t_f			160	_	ns
	Turn-off Time	toff			480	_	
Total Gate Charge (Gate-Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = 40 \text{ V}, V_{GS} = 10 \text{ V}$		135	_	nC
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{\mathrm{D}}=60~\mathrm{A}$		90	_] "[]
Gate-Drain ("Miller") Charge		$\mathbf{Q}_{\mathbf{gd}}$		_	45	_	

SOURCE-DRAIN RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current (Note 1)	$I_{ m DR}$	_	_	_	60	A
Pulse Drain Reverse Current (Note 1)	$I_{ m DRP}$	_	_	_	240	A
Forward Voltage (Diode)	$V_{ m DSF}$	$I_{DR} = 60 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.4	V
Reverse Recovery Time	t _{rr}	$I_{DR} = 60 \text{ A}, V_{GS} = 0 \text{ V}$	_	180	_	ns
Reverse Recovery Charge	Q_{rr}	$\mathrm{dI}_{\mathrm{DR}}$ / $\mathrm{dt}=50\mathrm{A}$ / $\mu\mathrm{s}$	_	0.32	_	μ C

MARKING



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